

# 承 認 書

## SPECIFICATION FOR APPROVAL

Customer Name: 2144

Description Part No.: \_\_\_\_\_

Customer Part No.: \_\_\_\_\_

Sample No.: \_\_\_\_\_

DDY Part No.: SFE201610-

DRAWING		
MADE	CHECKED	APPROVED
王海玲	赵万虎	肖中华
DATE: 2023年5月22日		

CUSTOMER APPROVE



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## 1. Scope

This specification applies to the SFE201610 Series of wire wound SMD power inductor.

## 2. PRODUCT IDENTIFICATION

SFE 201610 - 1R5 □ - □  
(1) (2) (3) (4) (5)

(1) .Series name (产品品名) (2) .Dimensions (产品尺寸)

(3) .Inductance value (电感值) (4) .Tolerance (误差值)

1R5: 1.5 $\mu$ H 221: 220 $\mu$ H

M:  $\pm$ 20%; N:  $\pm$ 30%

(5) .Environmental status (环保状态)

LF- Lead free; HF-Halogen free.

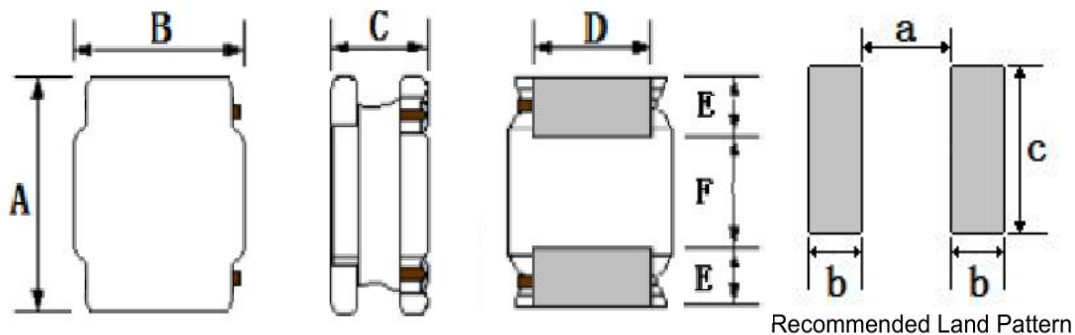
FP-Free red phosphor.

## 3. Electrical Characteristics

Please refer to Item 5.

- 1). Operating temperature range (individual chip without packing): -40 $^{\circ}$ C ~ +125 $^{\circ}$ C .
- 2). Storage temperature range (packaging conditions): -40 $^{\circ}$ C ~ +85 $^{\circ}$ C and RH 70% (Max.).
- 3). Rating DC current: Temperature rise( $\Delta$ T) is 40 $^{\circ}$ C approximately at Irms.
- 4). Saturation DC current: Inductance drop approximately 30% of L<sub>0</sub> at Isat.

## 4. Shape and Dimensions (Unit:mm)

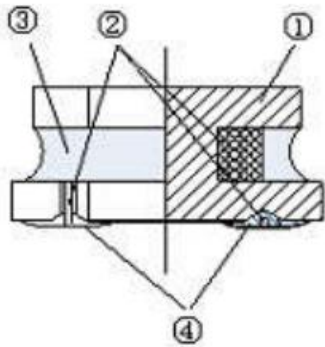


NO	Series	A	B	C	D	E	F	a Typ.	b Typ.	c Typ.
1	SFE201610	2.0 $\pm$ 0.3	1.6 $\pm$ 0.3	1.05 Max	1.2 $\pm$ 0.2	0.6 Typ.	0.8 Typ.	0.60	0.80	1.40





### 6. Structure (The structure of product.)



NO	Components	Material
①	Core	Ni-Zn Ferrite
②	Wire	Polyurethane system enameled copper wire
③	Magnetic Glue	Epoxy resin and magnetic powder
④	Plating	AgNiSn or FeNiCu + Sn Alloy

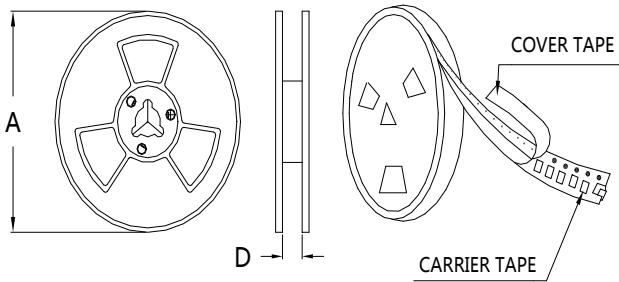
### 7. PACKAGING(unit: mm)

1.包装类型：编带装

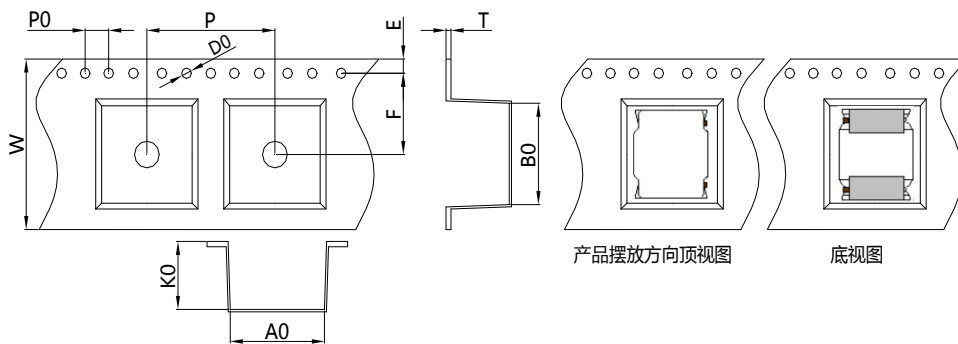
2.包装尺寸：

13" 盘

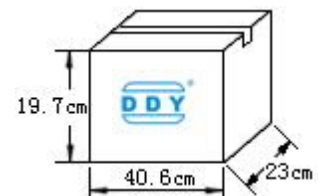
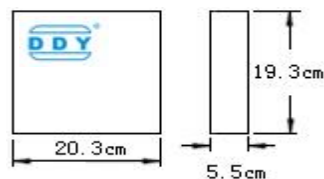
7" 盘



	13" 盘	7" 盘
A	$\Phi 330 \pm 2.0$	$\Phi 178 \pm 2.0$
D	8.5	



Size	Item	W	A0	B0	K0	P	T	E	F	D0	P0
2016	(mm)	$8.0 \pm 0.1$	$1.9 \pm 0.1$	$2.2 \pm 0.1$	$1.2 \pm 0.1$	$4.0 \pm 0.1$	$0.25 \pm 0.1$	$1.75 \pm 0.1$	$3.5 \pm 0.1$	$1.5 \pm 0.1$	$4.0 \pm 0.1$



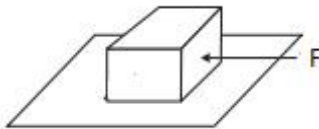
每卷 2000 Pcs

每盒 4卷,共 8000 Pcs

每箱 6盒,共 48000 Pcs



**8. RELIABILITY TEST**

No.	TEST ITEM	SPECIFICATION	TEST CONDITION
1	High temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (N: Follow the product specification for the setting.) Time : $96 \pm 2$ hours Place the samples for one hour at room temperature and test them within two hours
2	Low temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $-40^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (M: Follow the product specification for the setting) Time : $96 \pm 2$ hours Place the samples for one hour at room temperature and test them within two hours.
3	Humidity test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $40 \pm 2^{\circ}\text{C}$ , Humidity: $93 \pm 3\% \text{RH}$ Time : $96 \pm 2$ hours Place the samples for one hour at room temperature and test them within two hours
4	Solderability test	Terminals must have 95% minimum solder coverage	1. Dip pads in flux then dip in solder pot at $245 \pm 5^{\circ}\text{C}$ for 5 second. 2. Solder: lead free 3. Flux: rosin flux
5	Heat endurance of flow soldering	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	1. Refer to the above reflow curve and go through the reflow for twice. 2. The peak temperature : $260 + 0 / - 5^{\circ}\text{C}$
6	Vibration test	1. No significant defects in appearance. 2. No short and no open.	Apply frequency 10~55~10Hz and amplitude 1.5mm, 1 min/cycle in X Y and Z direction for 2 hours each. (total 6 hours)
7	Terminal strength push test	1. Applied force: 10N Duration: 10sec 2. Solder paste thickness: 0.12mm 3. Meet the above requirements without any loose termina	Solder the test samples to the PCB through $245^{\circ}\text{C}$ reflow, apply a standard force on the side of the test samples for 10 seconds. 



## 9. SOLDERING CONDITIONS

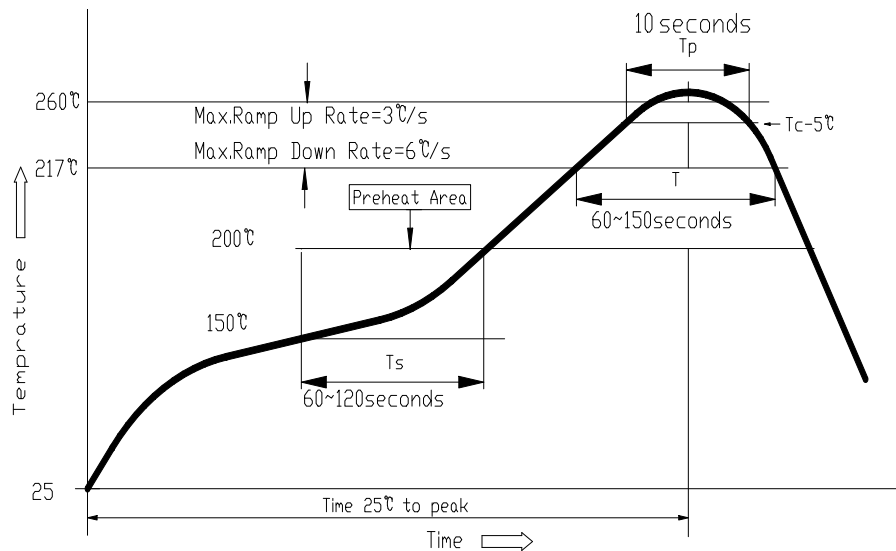
Applicable soldering process to the products is refl.

### 9.1 Soldering Materials

(1) Solder: Sn-3.0Ag-0.5Cu

(2) Flux: Use rosin-based flux, but not strongly acidic flux (with xhlorine exceeding 0.2wt%). Do not use water-soluble flux.

### 9.2 Reflow Soldering Profile



### 9.3 Soldering Iron

Reworking with electric soldering iron must preheating at 150°C for 1 minute is required, and do not directly touch the core with the tip of the soldering iron. The reworking soldering conditions are as follows.

- ① Temperature of soldering iron tip: 350°C;
- ② Soldering iron power output:  $\leq 30W$ ;
- ③ Diameter of soldering iron end:  $\leq 1.0mm$ ;
- ④ Soldering time:  $< 3s$

